

to be contacted, the contact unit being coaxially received in a through hole formed in an insulating support member, characterized by that:

the through hole having a first diameter in an intermediate portion positioned between first and second axial ends and a reduced diameter portion adjacent at least one of the axial ends;

the contact unit in the form of a coil spring comprising a coil spring portion having a coarsely wound portion positioned in the intermediate portion of the through hole and at least one electrode pin portion comprising a closely wound portion at one end of the coil spring portion, the closely wound portion having a tapered or stepped shape so as to be prevented from coming off by the reduced diameter portion;

only the closely wound portion of the contact unit being surface processed so as to include a first layer of electroconductive material that covers an outer surface defined by a plurality of turns of the closely wound portion of the coil spring in a continuous manner.

9. An electroconductive contact unit assembly according to claim 8, wherein the reduced diameter portion comprises a tapered hole section provided at each axial end of the through hole, and the electrode pin portion is formed at each end of the coil spring portion, and is tapered in shape and closely wound so as to be prevented from coming off by the corresponding tapered hole section of the through hole.

10. (Amended) An electroconductive contact unit assembly according to claim 8, wherein the reduced diameter portion has a smaller inner diameter than an outer diameter of the coil spring portion, and is provided at each axial end of the through hole.

11. An electroconductive contact unit assembly according to claim 8, wherein the coil spring portion is wound at a uniform pitch.

12. An electroconductive contact unit assembly according to claim 8, wherein the electrode pin portions are each closely wound with a pre-stress.

13. An electroconductive contact unit assembly according to claim 11, wherein the electrode pin portions are each closely wound with a pre-stress.

14. An electroconductive contact unit according to claim 8, wherein the surface processing is conducted after the coil spring portion and electrode pin portions are formed out of a wire member.

15. An electroconductive contact unit according to claim 11, wherein the surface processing is conducted after the coil spring portion and electrode pin portions are formed out of a wire member.

16. An electroconductive contact unit according to claim 12, wherein the surface processing is conducted after the coil spring portion and electrode pin portions are formed out of a wire member.

17. An electroconductive contact unit according to claim 13, wherein the surface processing is conducted after the coil spring portion and electrode pin portions are formed out of a wire member.

18. An electroconductive contact unit according to claim 14, wherein the surface processing is conducted after the coil spring portion and electrode pin portions are formed out of a wire member.

19. An electroconductive contact unit according to claim 8, wherein the surface processing is conducted both before and after the coil spring portion and electrode pin portions are formed out of a wire member.

20. An electroconductive contact unit according to claim 11, wherein the surface processing is conducted both before and after the coil spring portion and electrode pin portions are formed out of a wire member.

21. An electroconductive contact unit according to claim 12, wherein the surface processing is conducted both before and after the coil spring portion and electrode pin portions are formed out of a wire member.

22. An electroconductive contact unit according to claim 13, wherein the surface processing is conducted both before and after the coil spring portion and electrode pin portions are formed out of a wire member.

Please add new claims 23-31 as set forth below:

23. (New) An electroconductive contact unit assembly according to claim 8, wherein the layer of electroconductive material comprises a plated layer.

24. (New) An electroconductive contact unit assembly according to claim 8, wherein the electroconductive material comprises a member selected from a group consisting of gold, nickel and copper.

25. (New) An electroconductive contact unit assembly according to claim 8, wherein each turn of a wire member that forms the coil spring includes a second layer of electroconductive material, and further wherein the second layer of electroconductive material is beneath the first layer of electroconductive material.

26. (New) A method for making an electroconductive contact unit in the form of a coil spring for resiliently contacting an object to be contacted in an electroconductive contact unit assembly, comprising the steps of:

preparing a coil spring including a coil spring portion comprising a coarsely wound portion and at least one electrode pin portion comprising a closely wound portion formed at one end of the coil spring portion and tapered or stepped in shape;

surface processing a portion of the closely wound portion to form a layer of electroconductive material that covers an outer surface defined by a plurality of turns of the closely wound portion of the coil spring.

27. (New) A method for making an electroconductive contact unit according to claim 26, further comprising the step of surface processing a coil wire for the coil spring to form an underlying layer of electroconductive layer on the coil wire before winding the coil wire into the coil spring.

28. (New) A method for making an electroconductive contact unit according to claim 26, wherein the layer of electroconductive material comprises a plated layer.

29. (New) A method for making an electroconductive contact unit according to claim 27, wherein the underlying layer of electroconductive material comprises a plated layer.

30. (New) An electroconductive contact unit according to claim 26, wherein the electroconductive material comprises a member selected from a group consisting of gold, nickel and copper.

31. (New) An electroconductive contact unit according to claim 27, wherein the electroconductive material of the underlying layer comprises a member selected from a group consisting of gold, nickel and copper.